

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6055844

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAKAYUKI NAKAJIMA	11/14/2019
ATSUSHI NAKAMURA	11/14/2019
YUJI SEKINO	11/18/2019
RECEIVING PARTY DATA	
Name:	LUMENTUM JAPAN, INC.
Street Address:	4-1-55 OYAMA, CHUO-KU
City:	SAGAMIHARA, KANAGAWA
State/Country:	JAPAN
Postal Code:	252-5250
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16845235
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	0100-0266
NAME OF SUBMITTER:	JOSHUA HAUSER
SIGNATURE:	/Joshua Hauser/
DATE SIGNED:	04/10/2020
Total Attachments: 1	
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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Lumentum Japan, Inc.
a corporation organized under the laws of Japan,
located at 4-1-55 Oyama, Chuo-ku, Sagami-hara, Kanagawa, 252-5250 Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said Lumentum Japan, Inc.
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**MODULATION DOPED SEMICONDUCTOR LASER AND MANUFACTURING METHOD
THEREFOR**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Lumentum Japan, Inc.
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Lumentum Japan, Inc.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	<u>中島 崇之</u>	<u>14, November, 2019</u>
	Takayuki NAKAJIMA	
2)	<u>中村 厚</u>	<u>14, November, 2019</u>
	Atsushi NAKAMURA	
3)	<u>関野 裕司</u>	<u>18, November, 2019</u>
	Yuji SEKINO	
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____